TermoPasty®

TECHNICAL DATA SHEET

Thermal conductive paste HP

Indispensable product for devices requiring efficient heat dissipation. This product provides effective heat dissipation and protection against environmental factors. With a thermal conductivity of 1.5 W/mK, it ensures optimal cooling, preventing key components from overheating. Its flexible formula offers broad application possibilities and reliable performance even in demanding environments. The product is electrically non-conductive, resistant to moisture and external influences.

Product features:

- thermal conductivity: 1.5 W/mK,
- high temperature resistance,
- resistant to oxidation, aqueous solutions, acids, bases, sulfur dioxide, and ammonia,
- excellent dielectric properties,
- versatile applications,
- easy application.

Applications:

- modules with high thermal conductivity,
- cooling devices on terminal plates or frames,
- high-speed and high-performance memory drives such as HDD & DVD,
- Steering system components in the automotive industry,
- power converters, electronic and electrical devices,
- laptops and computers, network communication devices,
- high-power LED diodes,
- RTV and household appliances, air conditioning units.

Physicochemical properties	
Appearance	White paste
Density at 20°C	~2.1 g/cm ^{3}
Thermal conductivity	>1.5 W/mK
Operating temperature range	-50°C to 250°C
Thermal impedance	<0.227°C in^2/W
Evaporation	0.001%
Bleed	0.05%
Viscosity	Non-fluid
Thixotropic index	380±10
Volume resistivity (ASTM D257)	1.3*10^{12} ρ_v Ω x m 1.3*10^{14} Ω x cm
Dielectric loss factor tg δ (ASTM D150)	0.024 (120 Hz) 0.021 (1 kHz) 0.015 (10 kHz) 0.005 (100 kHz)
Relative dielectric permeability ε_r (ASTM D150)	7.7 (120 Hz) 7.6 (1 kHz) 7.4 (10 kHz) 7.2 (100 kHz)
Shelf life	3 years

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Compatibility:

Silicone Paste HP is suitable for use with most electronic devices and metal surfaces. Its electrically non-conductive formula ensures safe operation with delicate electronic circuits.

Application method	
Machine application	Yes
Stencil	Yes
Spatula	Yes
Tube	Yes
Cartouche gun	Yes

Usage instructions:

Restricted to professional users. Read SDS carefully prior to use.

Before application, ensure that the surface is clean and dry. Apply a small amount of paste to the component using a spreading tool. Distribute a thin, even layer, ensuring full contact with heat-dissipating elements to maximize thermal conductivity. After application, close the container to prevent the paste from drying out.

Package	
Tube	7 g (ART.AGT-284) - 10/300 pcs.*
Cartouche	60 g (ART.AGT-125) - 5 pcs.*
Plastic box	100 g (ART.AGT-127) - 8 pcs.* 1 kg (ART.AGT-113) - 1 pc.*

*Quantity of pcs. in a bulk package.

Storage:

Store in a well-ventilated, cool, and dry place. Keep containers tightly sealed when not in use. Protect from direct sunlight.

Technical support:

AG TermoPasty provides technical support, answering questions about the technical specifications and applications of our products. Please contact us via email at info@termopasty.pl.

Note:

The data presented in this document reflect our current state of knowledge and describe the typical properties and applications of the product. However, the responsibility for determining the suitability of this product for specific applications lies with the user. AG TermoPasty is not liable for the results of the product's use, as the conditions of its application are beyond our control.